

## 1、Description

Glass passivated high commutation triacs in a full pack, plastic envelope intended for use in circuits where high static and dynamic  $dV/dt$  and high  $di/dt$  can occur. These devices will commutate the full rated rms current at the maximum rated junction temperature, without the aid of a snubber.

## 2、Applications

Typical applications include motor control, industrial and domestic lighting, heating and static switching.

- Heating regulation
- Motor control
- Phase control

## 3、Features

- Blocking voltage to 800 V
- On-state RMS current to 12A
- Ultra low gate trigger current
- Low cost package.

## 4、Pinning information

PIN	Description	Simplified outline	Symbol
1	main terminal 1 ( T1 )	 TO-220	
2	main terminal 2 ( T2 )		
3	gate ( G )		
tab	main terminal 2 ( T2 )		

## 5、Quick reference data

SYMBOL	PARAMETER	MAX	UNIT
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltages	800	V
$I_{T(RMS)}$	RMS on-state current	12	A
$I_{TSM}$	Non-repetitive peak on-state current	90	A

## 6、Thermal characteristics

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{th j-mb}$	Thermal resistance junction to mounting base	full cycle	-	-	1.5	K/W
		half cycle	-	-	2.0	K/W
$R_{th j-a}$	Thermal resistance junction to ambient	in free air		60	-	K/W

## 7. Limiting value

Limiting values in accordance with the Maximum System(IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT	
$V_{DRM} V_{RRM}$	Repetitive peak off-state voltages		-	800	V	
$I_T(RMS)$	RMS on-state current	full sine wave; $T_{mb} \leq 102^\circ C$	-	12	A	
	Non-repetitive peak on-state current	full sine wave; $T_j = 25^\circ C$ prior to surge	$t = 20 \text{ ms}$	-	90	A
			$t = 16.7 \text{ ms}$	-	105	A
$I^2t$	$I^2t$ for fusing	$t = 10 \text{ ms}$	-	45	$\text{A}^2\text{s}$	
$dI_T/dt$	Repetitive rate of rise of on-state current after triggering	$I_{TM} = 12 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A/s}$				
			$T2+ G+$	-	100	$\text{A}/\mu\text{s}$
			$T2+ G-$	-	100	$\text{A}/\mu\text{s}$
			$T2- G-$	-	100	$\text{A}/\mu\text{s}$
$I_{GM}$	Peak gate current		-	2	A	
$V_{GM}$	Peak gate voltage		-	8	V	
$P_{GM}$	Peak gate power		-	16	W	
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.35	W	
$T_{stg}$	Storage temperature		-40	150	$^\circ C$	
$T_j$	Junction temperature		-40	125	$^\circ C$	

## 8. Characteristics

$T_j = 25^\circ C$  unless otherwise stated

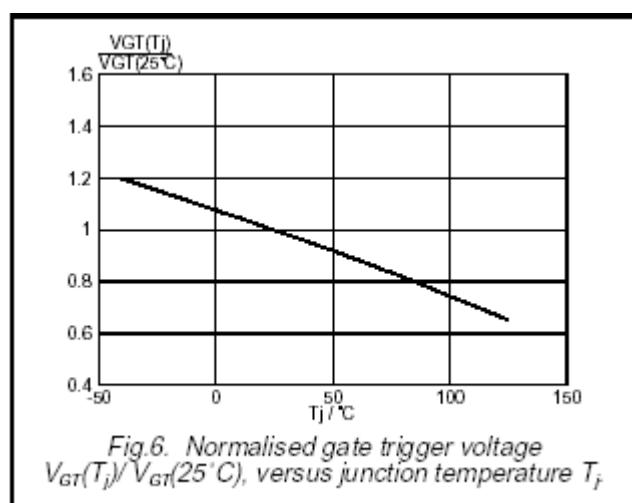
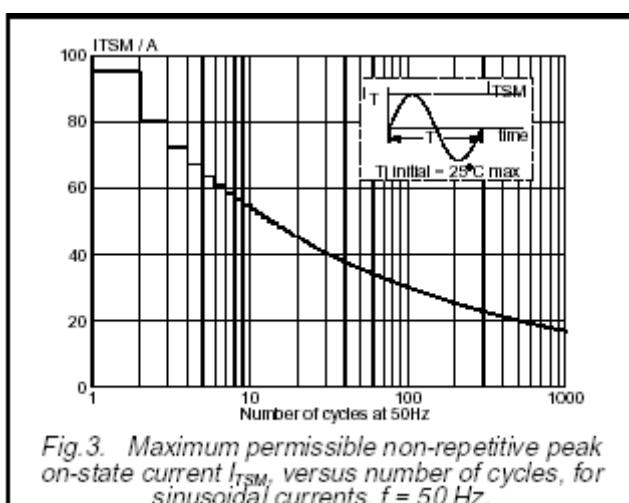
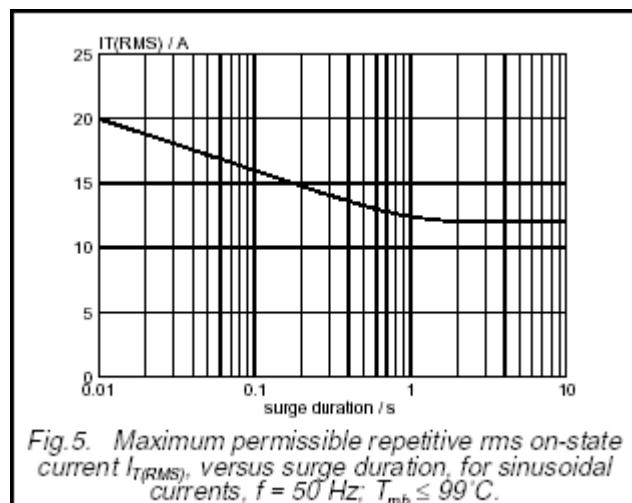
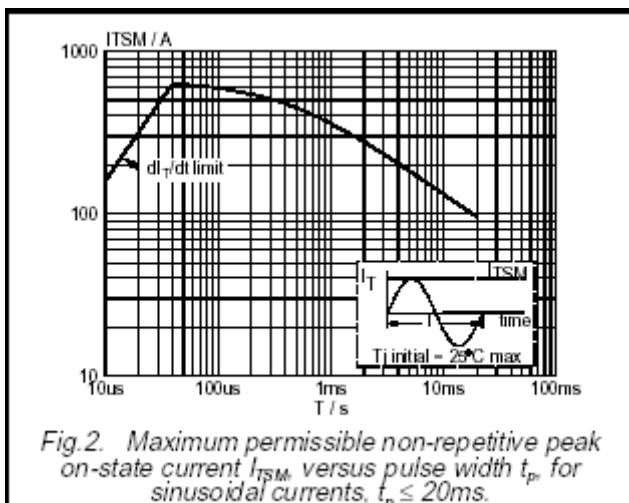
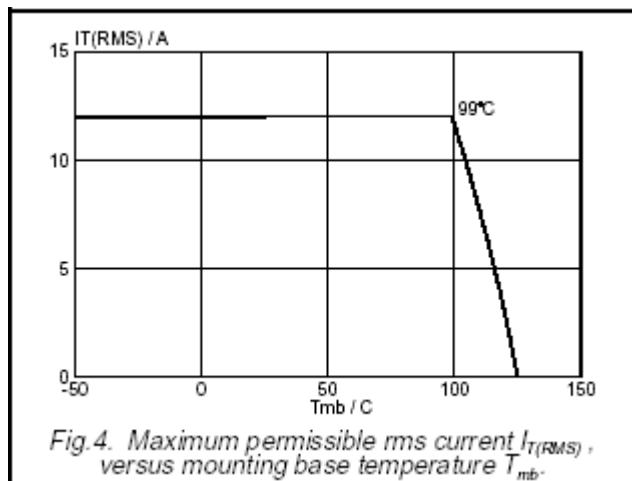
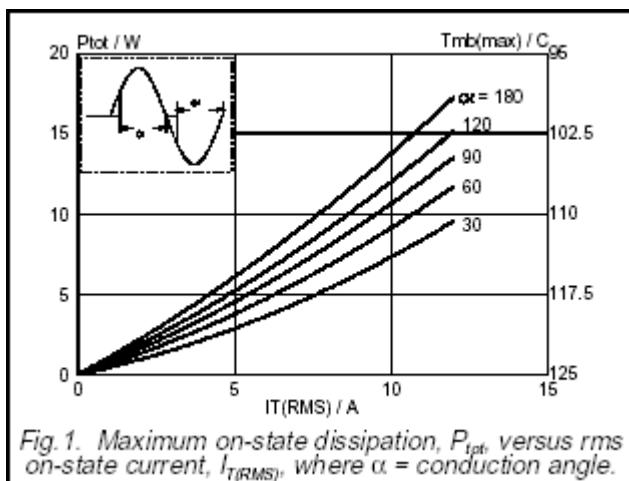
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	
<b>Static characteristics</b>							
$I_{GT}$	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$					
		$T2+ G+$	3.0	8	10	mA	
		$T2+ G-$	3.0	8	10	mA	
		$T2- G-$	3.0	8	10	mA	
$I_L$	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$					
		$T2+ G+$	-	10	30	mA	
		$T2+ G-$	-	20	50	mA	
		$T2- G-$	-	10	30	mA	
$I_H$	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.15 \text{ A}$	-	10	20	mA	
$V_T$	On-state voltage	$I_T = 17 \text{ A}$	-	-	1.85	V	
$V_{GT}$	Gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$					
			$T2+ G+$	0.5	0.78	1.5	V
			$T2+ G-$	0.5	0.70	1.5	V
			$T2- G-$	0.5	0.71	1.5	V

### Dynamic Characteristics

$dV_D/dt$	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125^\circ C;$ Exponential wave form; gate open circuit	250	500	-	$\text{V}/\mu\text{s}$
$dl_{com}/dt$	Critical rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 125^\circ C$ $I_{(RMS)} = 4.4 \text{ A};$ Commutating $dv/dt = 18 \text{ V}/\text{s},$ Without snubber; gate open circuit	6.5	-	-	$\text{A}/\text{ms}$
$dl/dt$	Repetitive Critical Rate of Rise of On-State Current	$I_{PK} = 50 \text{ A}; PW = 40 \text{ sec}; dl/dt = 200 \text{ mA}/\text{sec}; f = 60 \text{ Hz}$	-	-	10	$\text{A}/\mu\text{s}$

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## 9. Electrical Characteristics Curve



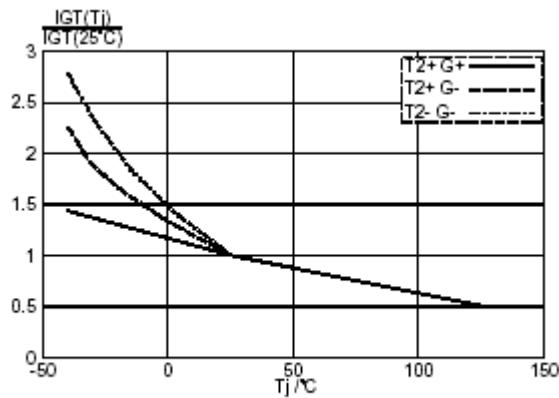


Fig. 7. Normalised gate trigger current  $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

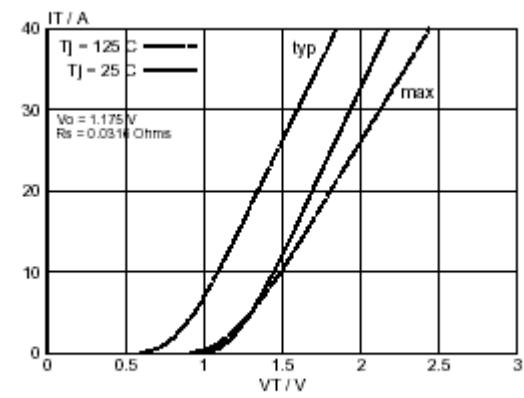


Fig. 10. Typical and maximum on-state characteristic.

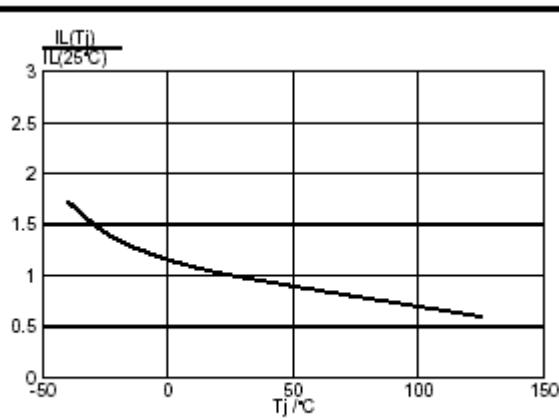


Fig. 8. Normalised latching current  $I_L(T_j)/I_L(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

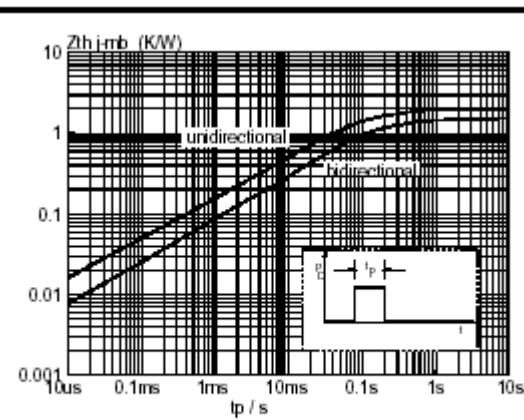


Fig. 11. Transient thermal impedance  $Z_{th,jmb}$ , versus pulse width  $t_p$ .

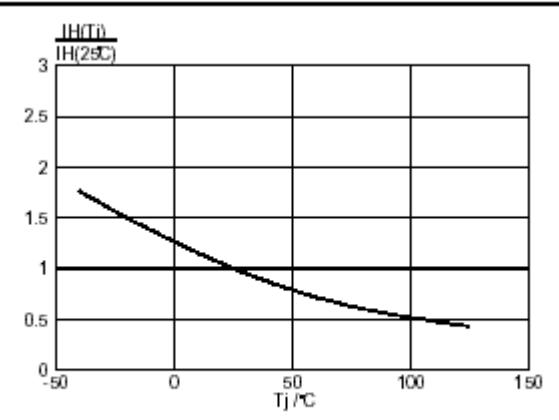


Fig. 9. Normalised holding current  $I_H(T_j)/I_H(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

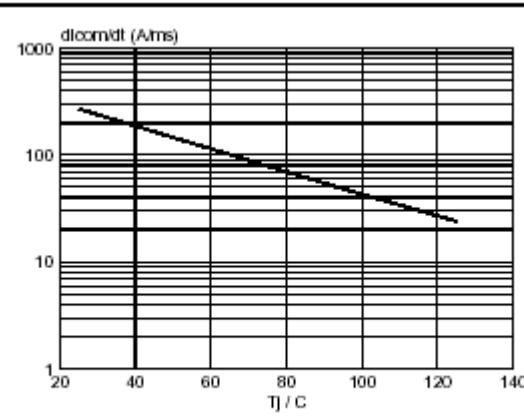
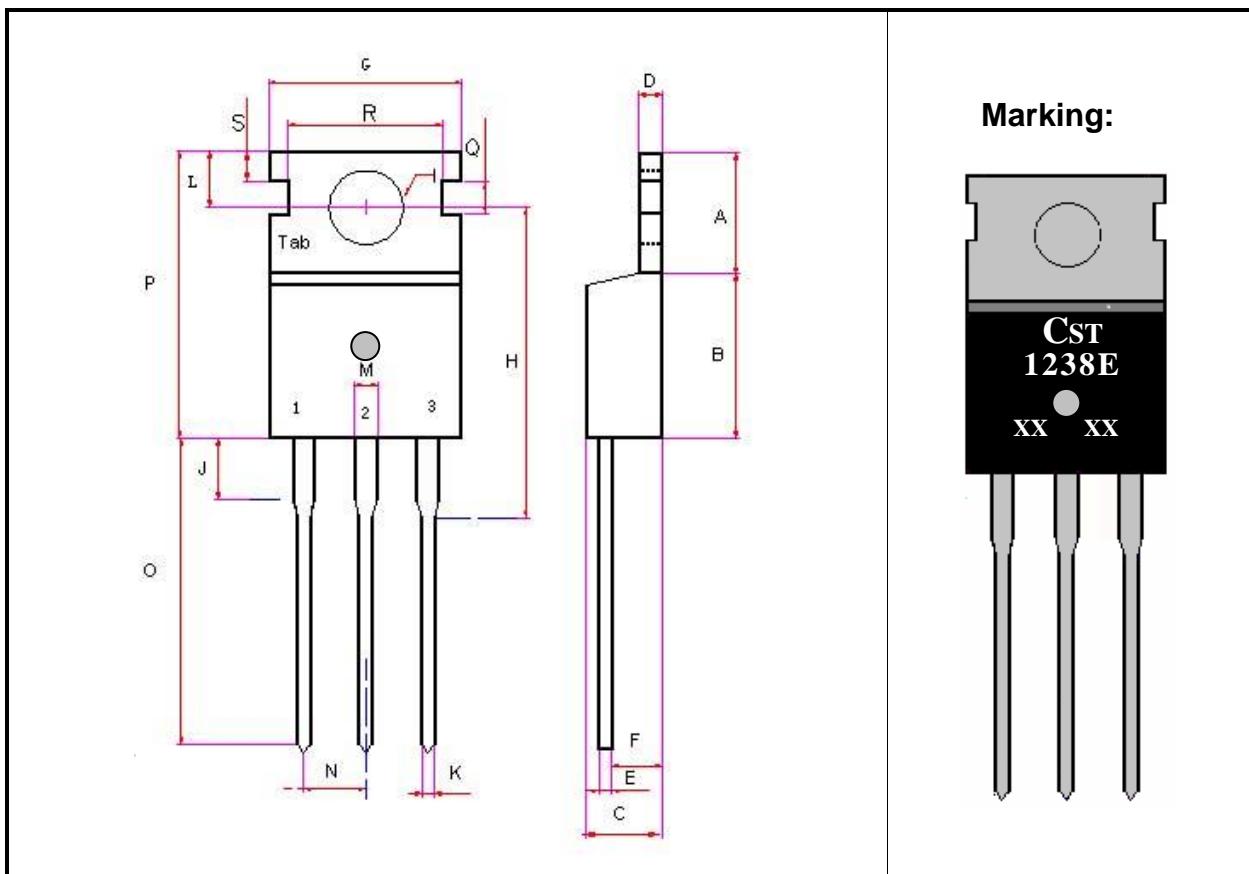


Fig. 12. Typical, critical rate of change of commutating current  $dI_{com}/dt$  versus junction temperature.

## 10、Package outline(TO-220)



DIM	Inches			Millimeters		
	Min	Type	Max	Min	Type	Max
A	0.226	0.258	0.301	5.75	6.55	7.65
B	0.349	0.362	0.369	8.86	9.20	9.38
C	0.171	0.178	0.183	4.35	4.53	4.65
D	0.046	0.051	0.055	1.16	1.30	1.40
E	0.018	0.020	0.026	0.45	0.51	0.65
F	0.070	0.094	0.105	1.785	2.40	2.675
G	0.367	0.394	0.415	9.31	10.00	10.55
H	-	-	0.640	-	-	16.25
I	-	0.143	0.152	-	3.62	3.85
J	0.087	0.108	0.127	2.22	2.75	3.22
K	0.027	0.031	0.035	0.68	0.8	0.88
L	0.093	-	0.128	2.36	-	3.24
M	0.046	0.048	0.057	1.18	1.22	1.44
N	-	0.100	0.104	-	2.54	2.65
O	0.485	0.514	0.546	12.32	13.05	13.88
P	0.593	0.616	0.648	15.07	15.65	16.47
Q	0.057	0.067	0.073	1.46	1.7	1.86
R	0.320	0.344	0.360	8.14	8.75	9.14
S	0.046	0.051	0.058	1.17	1.3	1.47